



## **Ferrites and accessories**

ER 11/5  
Planar cores in sets and accessories

**Series/Type:**            **B65525, B65526**

**Date:**                    **October 2022**

**ER 11/5**
**Planar core**
**B65525**

- To IEC 63093-9
- For transformers featuring high inductance and low overall height
- Delivery mode: sets

**Magnetic characteristics (per set)**

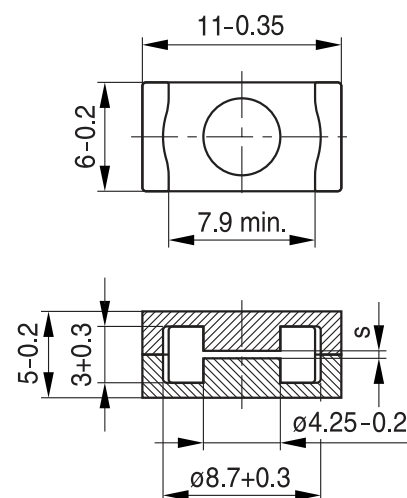
$$\Sigma l/A = 1.1 \text{ mm}^{-1}$$

$$l_e = 14.1 \text{ mm}$$

$$A_e = 12.4 \text{ mm}^2$$

$$A_{\min} = 10.3 \text{ mm}^2$$

$$V_e = 174 \text{ mm}^3$$

**Approx. weight 0.85 g/set**


FEK0531-8

**Ungapped**

Material	$A_L$ value nH	$\mu_e$	Ordering code
PC200	640 +30/-20%	580	B65525J0000R608
N49	800 +30/-20%	715	B65525J0000R049
N92	900 +30/-20%	814	B65525J0000R092
N87	1200 +30/-20%	1050	B65525J0000R087
N97	1200 +30/-20%	1086	B65525J0000R097
T38	6400 +40/-30%	5600	B65525J0000Y038

**Gapped ( $A_L$  values/air gaps examples)**

Material	$A_L$ value nH	s approx. mm	$\mu_e$	Ordering code
N87	160 ±3%	0.08	140	B65525J0160A087
	100 ±3%	0.14	90	B65525J0100A087

 Other  $A_L$  values/air gaps and materials available on request – see Processing remarks on page 4.


**SMD coil former with gullwing terminals**

Material: GFR liquid crystal polymer (UL 94 V-0, insulation class to IEC 60085: F  $\geq$  max. operating temperature 155 °C), color code black  
Zenite 7130® [E344082 (M)], CELANESE INTERNATIONAL CORP.

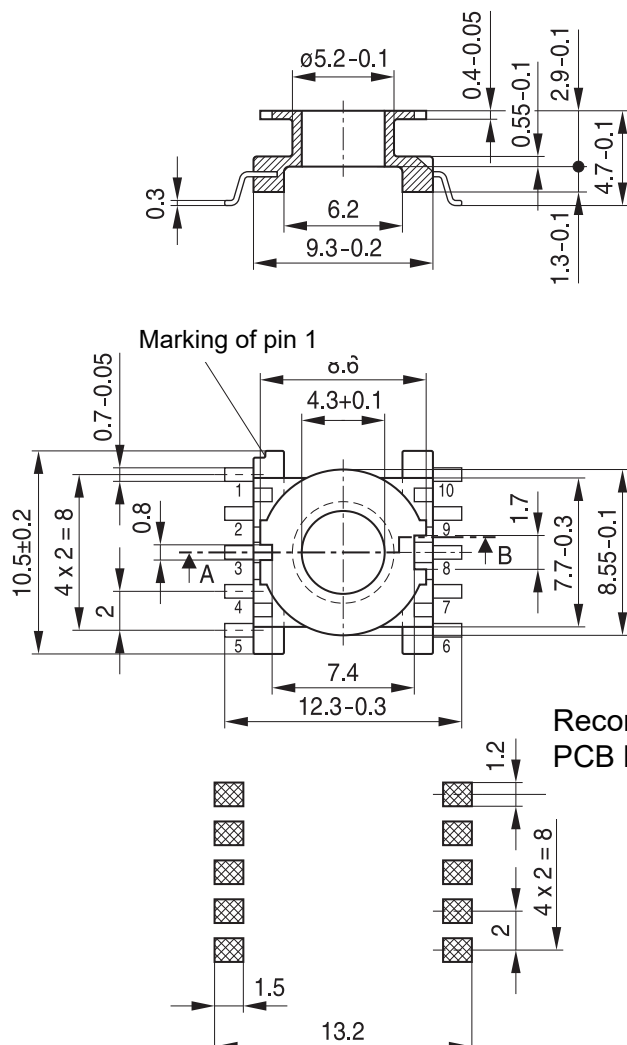
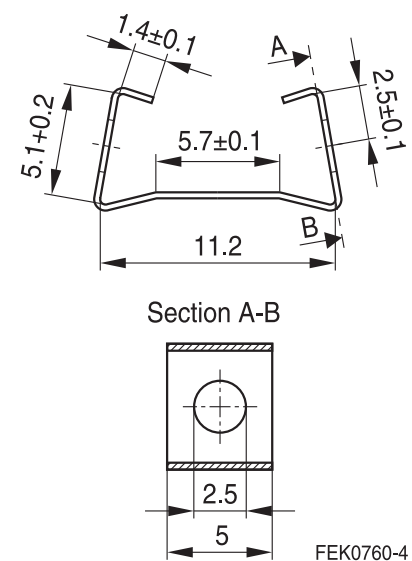
Solderability: to IEC 60068-2-58, test Td, method 6 (Group 3): 245 °C, 3 s

Resistance to soldering heat: to IEC 60068-2-58, test Td, method 6 (Group 3): 255 °C, 10 s  
permissible soldering temperature for wire-wrap connection on coil former: 400 °C, 1 s

Winding: see Processing notes, 2.1

**Yoke** Material: Stainless spring steel (0.15 mm)

Coil former					Ordering code
Sections	$A_N$ mm <sup>2</sup>	$l_N$ mm	$A_R$ value $\mu\Omega$	Terminals	
1	3.3	21.6	225	10	B65526B1010T001
Yoke					B65526A2000X000

**Coil former**

**Yoke**


FEK0759-V-D

## Ferrites and accessories

### Cautions and warnings

#### Mechanical stress and mounting

Ferrite cores have to meet mechanical requirements during assembling and for a growing number of applications. Since ferrites are ceramic materials one has to be aware of the special behavior under mechanical load.

As valid for any ceramic material, ferrite cores are brittle and sensitive to any shock, fast temperature changing or tensile load. Especially high cooling rates under ultrasonic cleaning and high static or cyclic loads can cause cracks or failure of the ferrite cores.

For detailed information see data book, chapter “*General - Definitions, 8.1*”.

#### Effects of core combination on $A_L$ value

Stresses in the core affect not only the mechanical but also the magnetic properties. It is apparent that the initial permeability is dependent on the stress state of the core. The higher the stresses are in the core, the lower is the value for the initial permeability. Thus the embedding medium should have the greatest possible elasticity.

For detailed information see data book, chapter “*General - Definitions, 8.1*”.

#### Heating up

Ferrites can run hot during operation at higher flux densities and higher frequencies.

#### NiZn-materials

The magnetic properties of NiZn-materials can change irreversible in high magnetic fields.

#### Ferrite Accessories

Our ferrite accessories have been designed and evaluated only in combination with our ferrite cores. We explicitly point out that our ferrite accessories or our ferrite cores may not be compatible with those of other manufacturers. Any such combination requires prior testing by the customer and will be at the customer's own risk.

We assume no warranty or reliability for the combination of our ferrite accessories with cores and other accessories from any other manufacturer.

#### Processing remarks

The start of the winding process should be soft. Else the flanges may be destroyed.

- Too strong winding forces may blast the flanges or squeeze the tube that the cores can not be mounted any more.
- Too long soldering time at high temperature (>300 °C) may effect coplanarity or pin arrangement.
- Not following the processing notes for soldering of the J-leg terminals may cause solderability problems at the transformer because of pollution with Sn oxyde of the tin bath or burned insulation of the wire. For detailed information see chapter “*Processing notes*”, section 2.2.
- The dimensions of the hole arrangement have fixed values and should be understood as a recommendation for drilling the printed circuit board. For dimensioning the pins, the group of holes can only be seen under certain conditions, as they fit into the given hole arrangement. To avoid problems when mounting the transformer, the manufacturing tolerances for positioning the customers' drilling process must be considered by increasing the hole diameter.

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## Ferrites and accessories

### Symbols and terms

Symbol	Meaning	Unit
A	Cross section of coil	mm <sup>2</sup>
A <sub>e</sub>	Effective magnetic cross section	mm <sup>2</sup>
A <sub>L</sub>	Inductance factor; $A_L = L/N^2$	nH
A <sub>L1</sub>	Minimum inductance at defined high saturation ( $\cong \mu_a$ )	nH
A <sub>min</sub>	Minimum core cross section	mm <sup>2</sup>
A <sub>N</sub>	Winding cross section	mm <sup>2</sup>
A <sub>R</sub>	Resistance factor; $A_R = R_{Cu}/N^2$	$\mu\Omega = 10^{-6} \Omega$
B	RMS value of magnetic flux density	Vs/m <sup>2</sup> , mT
$\Delta B$	Flux density deviation	Vs/m <sup>2</sup> , mT
$\hat{B}$	Peak value of magnetic flux density	Vs/m <sup>2</sup> , mT
$\Delta \hat{B}$	Peak value of flux density deviation	Vs/m <sup>2</sup> , mT
B <sub>DC</sub>	DC magnetic flux density	Vs/m <sup>2</sup> , mT
B <sub>R</sub>	Remanent flux density	Vs/m <sup>2</sup> , mT
B <sub>S</sub>	Saturation magnetization	Vs/m <sup>2</sup> , mT
C <sub>0</sub>	Winding capacitance	F = As/V
CDF	Core distortion factor	mm <sup>-4.5</sup>
DF	Relative disaccommodation coefficient $DF = d/\mu_i$	
d	Disaccommodation coefficient	
E <sub>a</sub>	Activation energy	J
f	Frequency	s <sup>-1</sup> , Hz
f <sub>cutoff</sub>	Cut-off frequency	s <sup>-1</sup> , Hz
f <sub>max</sub>	Upper frequency limit	s <sup>-1</sup> , Hz
f <sub>min</sub>	Lower frequency limit	s <sup>-1</sup> , Hz
f <sub>r</sub>	Resonance frequency	s <sup>-1</sup> , Hz
f <sub>Cu</sub>	Copper filling factor	
g	Air gap	mm
H	RMS value of magnetic field strength	A/m
$\hat{H}$	Peak value of magnetic field strength	A/m
H <sub>DC</sub>	DC field strength	A/m
H <sub>c</sub>	Coercive field strength	A/m
h	Hysteresis coefficient of material	10 <sup>-6</sup> cm/A
h/ $\mu_i^2$	Relative hysteresis coefficient	10 <sup>-6</sup> cm/A
I	RMS value of current	A
I <sub>DC</sub>	Direct current	A
$\hat{I}$	Peak value of current	A
J	Polarization	Vs/m <sup>2</sup>
k	Boltzmann constant	J/K
k <sub>3</sub>	Third harmonic distortion	
k <sub>3c</sub>	Circuit third harmonic distortion	
L	Inductance	H = Vs/A

**Ferrites and accessories**
**Symbols and terms**

Symbol	Meaning	Unit
$\Delta L/L$	Relative inductance change	H
$L_0$	Inductance of coil without core	H
$L_H$	Main inductance	H
$L_p$	Parallel inductance	H
$L_{rev}$	Reversible inductance	H
$L_s$	Series inductance	H
$l_e$	Effective magnetic path length	mm
$l_N$	Average length of turn	mm
$N$	Number of turns	
$P_{Cu}$	Copper (winding) losses	W
$P_{trans}$	Transferrable power	W
$P_V$	Relative core losses	mW/g
PF	Performance factor	
$Q$	Quality factor ( $Q = \omega L/R_s = 1/\tan \delta_L$ )	
$R$	Resistance	$\Omega$
$R_{Cu}$	Copper (winding) resistance ( $f = 0$ )	$\Omega$
$R_h$	Hysteresis loss resistance of a core	$\Omega$
$\Delta R_h$	$R_h$ change	$\Omega$
$R_i$	Internal resistance	$\Omega$
$R_p$	Parallel loss resistance of a core	$\Omega$
$R_s$	Series loss resistance of a core	$\Omega$
$R_{th}$	Thermal resistance	K/W
$R_V$	Effective loss resistance of a core	$\Omega$
$s$	Total air gap	mm
$T$	Temperature	$^{\circ}\text{C}$
$\Delta T$	Temperature difference	K
$T_C$	Curie temperature	$^{\circ}\text{C}$
$t$	Time	s
$t_v$	Pulse duty factor	
$\tan \delta$	Loss factor	
$\tan \delta_L$	Loss factor of coil	
$\tan \delta_r$	(Residual) loss factor at $H \rightarrow 0$	
$\tan \delta_e$	Relative loss factor	
$\tan \delta_h$	Hysteresis loss factor	
$\tan \delta/\mu_i$	Relative loss factor of material at $H \rightarrow 0$	
$U$	RMS value of voltage	V
$\hat{U}$	Peak value of voltage	V
$V_e$	Effective magnetic volume	$\text{mm}^3$
$Z$	Complex impedance	$\Omega$
$Z_n$	Normalized impedance $ Z _n =  Z /N^2 \times \varepsilon (l_e/A_e)$	$\Omega/\text{mm}$

## Ferrites and accessories

### Symbols and terms

Symbol	Meaning	Unit
$\alpha$	Temperature coefficient (TK)	1/K
$\alpha_F$	Relative temperature coefficient of material	1/K
$\alpha_e$	Temperature coefficient of effective permeability	1/K
$\epsilon_r$	Relative permittivity	
$\Phi$	Magnetic flux	Vs
$\eta$	Efficiency of a transformer	
$\eta_B$	Hysteresis material constant	mT <sup>-1</sup>
$\eta_i$	Hysteresis core constant	A <sup>-1</sup> H <sup>-1/2</sup>
$\lambda_s$	Magnetostriction at saturation magnetization	
$\mu$	Relative complex permeability	
$\mu_0$	Magnetic field constant	Vs/Am
$\mu_a$	Relative amplitude permeability	
$\mu_{app}$	Relative apparent permeability	
$\mu_e$	Relative effective permeability	
$\mu_i$	Relative initial permeability	
$\mu_p'$	Relative real (inductive) component of $\bar{\mu}$ (for parallel components)	
$\mu_p''$	Relative imaginary (loss) component of $\bar{\mu}$ (for parallel components)	
$\mu_r$	Relative permeability	
$\mu_{rev}$	Relative reversible permeability	
$\mu_s'$	Relative real (inductive) component of $\bar{\mu}$ (for series components)	
$\mu_s''$	Relative imaginary (loss) component of $\bar{\mu}$ (for series components)	
$\mu_{tot}$	Relative total permeability derived from the static magnetization curve	
$\rho$	Resistivity	$\Omega\text{m}^{-1}$
$\Sigma l/A$	Magnetic form factor	mm <sup>-1</sup>
$\tau_{Cu}$	DC time constant $\tau_{Cu} = L/R_{Cu} = A_L/A_R$	s
$\omega$	Angular frequency; $\omega = 2 \pi f$	s <sup>-1</sup>

All dimensions are given in mm.

**SMD** Surface-mount device



## Important notes

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1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule, we are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether a product with the properties described in the product specification is suitable for use in a particular customer application.
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